

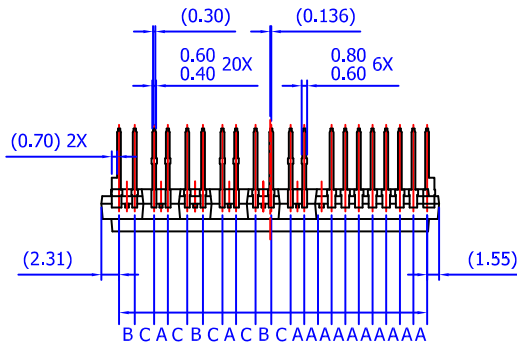
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



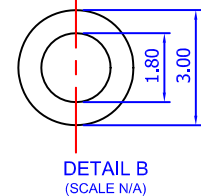
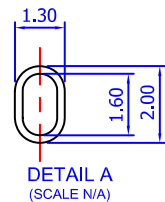
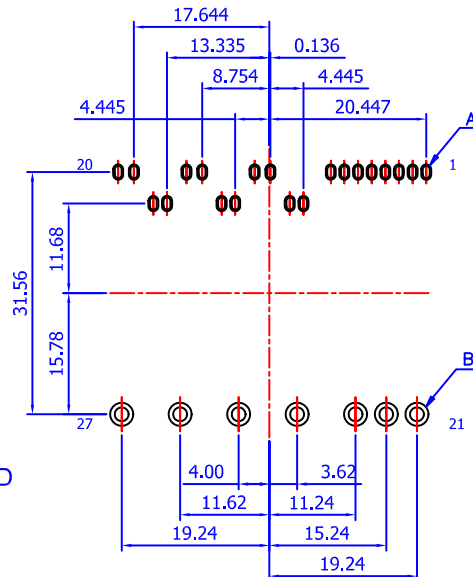
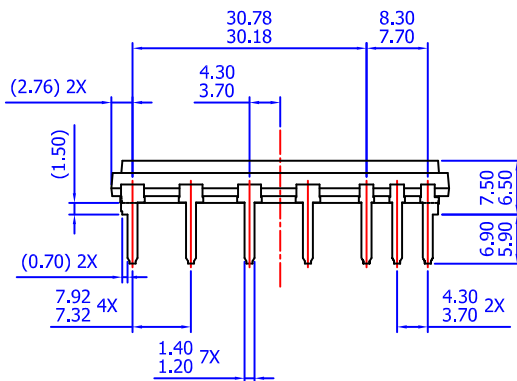
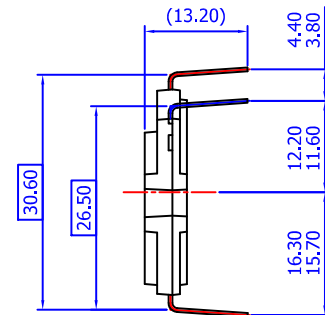
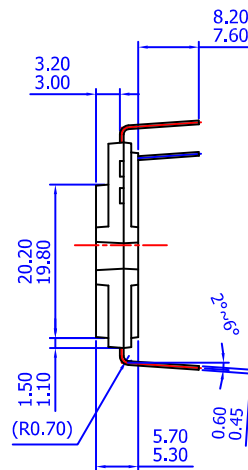
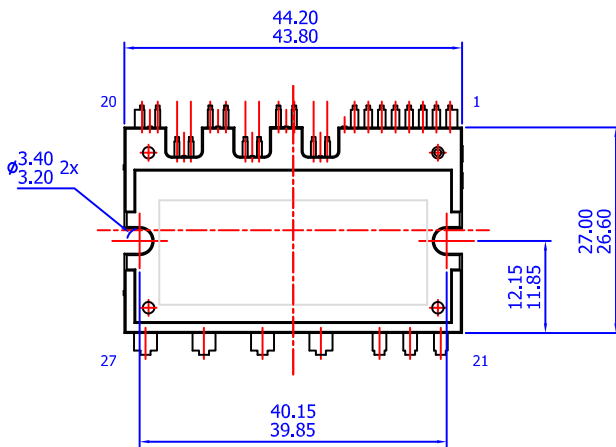
## SPMCA-027 / PDD STD, SPM27-CA, DBC TYPE CASE MODFJ ISSUE O

DATE 31 JAN 2017



LEAD PITCH (TOLERANCE : ±0.30)

- A : 1.778
- B : 2.050
- C : 2.531



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
  - B) ALL DIMENSIONS ARE IN MILLIMETERS
  - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
  - D) ( ) IS REFERENCE

### LAND PATTERN RECOMMENDATIONS

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<b>DESCRIPTION:</b>	<b>SPMCA-027 / PDD STD, SPM27-CA, DBC TYPE</b>	<b>PAGE 1 OF 1</b>

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